

LNJ026X8BRA1

High Bright Surface Mounting Chip LED

UTSS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	10	mA
Pulse forward current *	I_{FP}	40	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

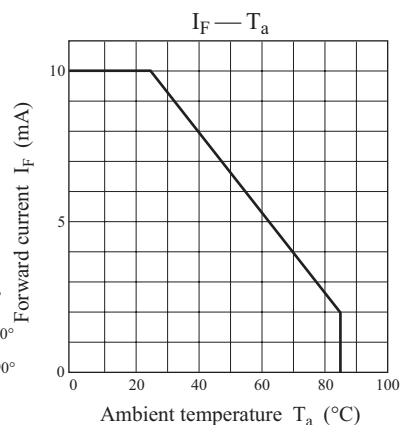
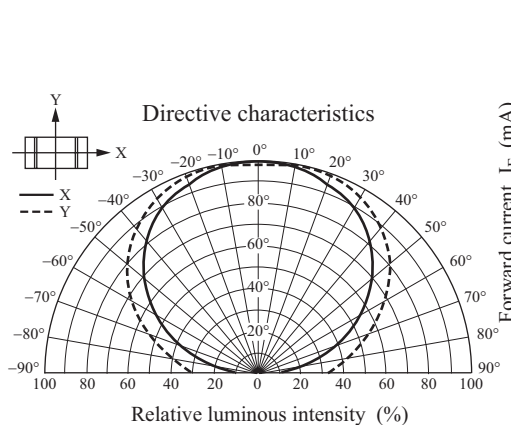
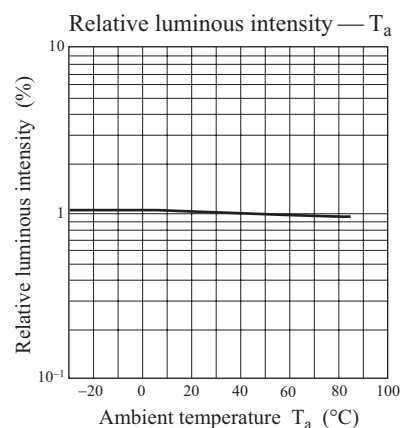
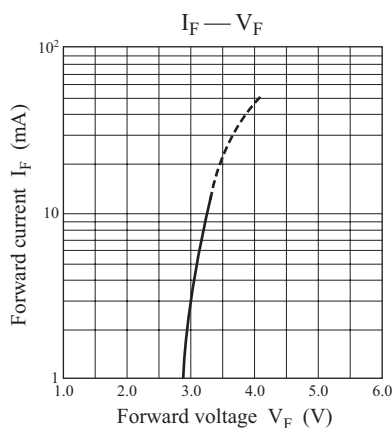
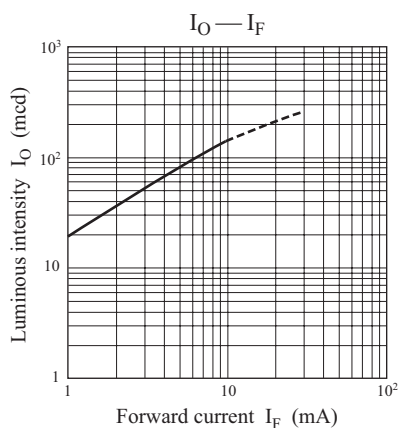
- White

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

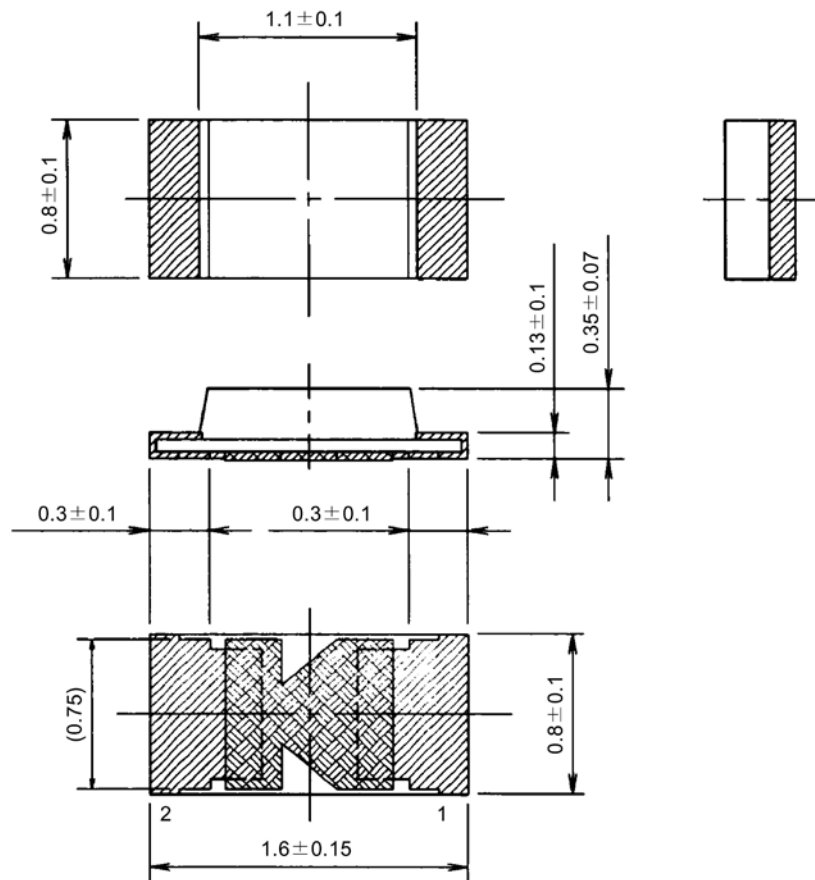
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 5 \text{ mA}$	36	80	170	mcd
Reverse current	I_R	$V_R = 5 \text{ V}$			10	μA
Forward voltage	V_F	$I_F = 5 \text{ mA}$		3.1	3.7	V
Chromaticity coordinates	x	$I_F = 5 \text{ mA}$	0.250		0.330	—
	y	$I_F = 5 \text{ mA}$	0.226		0.359	—

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFTN2K2600



- Pin name
 - 1: Anode
 - 2: Cathode

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